ABSTRACT OF THE DISCLOSURE

A multilayer printed wiring board which permits the formation of fine wiring patterns, thereby increasing the density of wiring patterns. Using photosensitive glass having a coefficient of thermal expansion close to that of a copper film as a core substrate, a through hole is formed in the photosensitive glass by photolithography, a sputtering silicon oxide layer and a sputtering silicon nitride layer are formed to prevent leak of alkali metal ions from the photosensitive glass, a sputtering chromium layer, a sputtering chromium-copper layer and a sputtering copper layer are formed to enhance the adhesion strength between the copper film and the sputtering silicon oxide layer, and a copper film of 1 to 20 μm thick is formed. With resin filled into the interior of the through hole, a wiring layer is patterned by etching, an insulating layer is formed, and the surface is covered with a surface treatment layer and a cover coat.